

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.328889**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006911	1000000	21013.1621094		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.111592	962000	339299.8125		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.003480	30000	10581.0742188		
		Silicon (Si)	7440-21-3	0.000754	1500	529.053710938		
		Magnesium (Mg)	7439-95-4	0.000174	1500	529.053710938		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.116000</b>	<b>1000000</b>	<b>352702.46875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.010584	1000000	32181.3828125		
		<b>External Plating Total:</b>				<b>0.010584</b>	<b>1000000</b>	<b>32181.3828125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000928	1000000	2821.61987305		
<b>Internal Plating Total:</b>				<b>0.000928</b>	<b>1000000</b>	<b>2821.61987305</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001636	750000	4974.32080078		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000545	250000	1657.09350586		
<b>Die Attach Total:</b>				<b>0.002181</b>	<b>1000000</b>	<b>6631.41503906</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.019673	103000	59816.5117188		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.170945	895000	519764.90625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000382	2000	1161.48571777		
		<b>Encapsulation Total:</b>				<b>0.191000</b>	<b>1000000</b>	<b>580742.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001285	1000000	3907.09179688		
					<b>TOTAL MASS (g) :</b>	<b>0.328889</b>		